

PMEG060T080CLPE

60 V, 2 x 4 A dual common cathode low leakage current Trench Schottky barrier rectifier

15 July 2024

Product data sheet

1. General description

Trench dual Schottky barrier rectifier in common cathode configuration encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Reverse voltage: V_R ≤ 60 V
- Forward current: I_F ≤ 4 A (per diode)
- Low forward voltage
- · Low leakage current due to Trench Schottky technology
- · Power and flat lead SMD plastic package
- Package height typical 0.95 mm
- · High power capability due to clip-bond technology

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- · Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- · Freewheeling applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit		
Per diode (unle	Per diode (unless otherwise specified)								
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 160 °C		-	-	4	A		
V _R	reverse voltage	T _j = 25 °C		-	-	60	V		
V _F	forward voltage	I _F = 4 A; T _j = 25 °C	[1]	-	580	660	mV		
I _R	reverse current	V _R = 10 V; T _j = 25 °C	[1]	-	0.14	0.9	μΑ		
		V _R = 60 V; T _j = 25 °C	[1]	-	0.3	1.8	μΑ		

[1] Very short pulse, in order to maintain a stable junction temperature.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode (diode 1)		CC
2	A2	anode (diode 2)	51	
3	CC	common cathode	3 2 2 CFP15B (SOT1289B)	A1 A2 006aab034

6. Ordering information

Table 3. Ordering information

Type number	Package						
	Name	Description	Version				
PMEG060T080CLPE		plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	<u>SOT1289B</u>				

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG060T080CLPE	060T
	L08C

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134).

Parameter	Conditions		Min	Max	Unit
ess otherwise specified)				•	
reverse voltage	T _j = 25 °C		-	60	V
forward current	δ = 1; T _{sp} ≤ 156 °C		-	5.7	Α
average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 160 °C		-	4	А
non-repetitive peak forward current	t_p = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C		-	80	Α
	t _p = 8.3 ms; half sine wave; per device; T _{j(init)} = 25 °C		-	150	А
e diode loaded		•		•	
total power dissipation	T _{amb} ≤ 25 °C	[1]	-	1.66	W
		[2]	-	2.15	W
junction temperature			-	175	°C
ambient temperature			-55	175	°C
storage temperature			-65	175	°C
	reverse voltage forward current average forward current non-repetitive peak forward current e diode loaded total power dissipation junction temperature ambient temperature	reverse voltage $T_j = 25 ^{\circ}\text{C}$ forward current $\delta = 1$; $T_{sp} \leq 156 ^{\circ}\text{C}$ average forward current $\delta = 0.5$; $f = 20 \text{kHz}$; square wave; $T_{sp} \leq 160 ^{\circ}\text{C}$ non-repetitive peak forward current $\delta = 0.5$;	reverse voltage $T_{j} = 25 ^{\circ}\text{C}$ forward current $\delta = 1$; $T_{sp} \leq 156 ^{\circ}\text{C}$ average forward current $\delta = 0.5$; $f = 20 \text{kHz}$; square wave; $T_{sp} \leq 160 ^{\circ}\text{C}$ non-repetitive peak forward current $t_{p} = 8.3 \text{ms}$; half sine wave; $T_{j(\text{init})} = 25 ^{\circ}\text{C}$ $t_{p} = 8.3 \text{ms}$; half sine wave; per device; $T_{j(\text{init})} = 25 ^{\circ}\text{C}$ e diode loaded $t_{p} = 0.3 \text{ms}$ total power dissipation $t_{p} = 0.3 \text{ms}$ for $t_{p} = 0.3 \text{ms}$; half sine wave; per device; $t_{p} = 0.3 \text{ms}$ for $t_{p} = 0.3 \text{ms}$ f	reverse voltage $T_j = 25 ^{\circ}\text{C}$ - forward current $\delta = 1$; $T_{sp} \leq 156 ^{\circ}\text{C}$ - average forward current $\delta = 0.5$; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $f = 20 ^{\circ}\text{KHz}$; square wave; $T_{sp} \leq 0.5$ - 0.5 ; $T_{sp} \leq 0.5$; $T_{sp} \approx 0.$	reverse voltage $T_j = 25 ^{\circ}\text{C}$ - 60 forward current $\delta = 1$; $T_{sp} \le 156 ^{\circ}\text{C}$ - 5.7 average forward current $\delta = 0.5$; $f = 20 \text{kHz}$; square wave; $T_{sp} \le 160 ^{\circ}\text{C}$ - 80 non-repetitive peak forward current $t_p = 8.3 \text{ms}$; half sine wave; $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 80 forward current $t_p = 8.3 \text{ms}$; half sine wave; per device; $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 150 redicted loaded $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 1.66 redicted power dissipation $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ - 1.75 ambient temperature - 1.75 redicted $t_{j(\text{init})} = 25 ^{\circ}\text{C}$ redicted $t_{j(\text{init})} = 25 ^$

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

^[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
	e diode loaded				- 7 P	111021	J
rei device, oii	e diode ioaded						
ui(j-a)	thermal resistance from	in free air	[1] [2]	-	-	90	K/W
	junction to ambient		[1] [3]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	7	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.

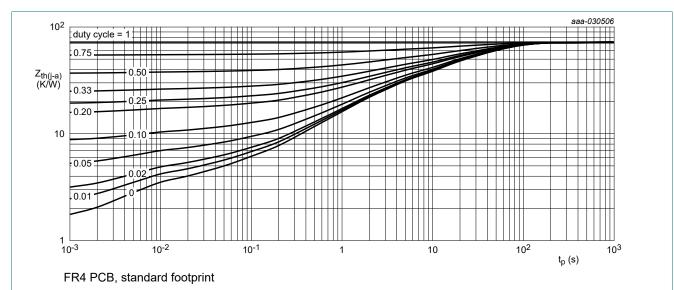


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

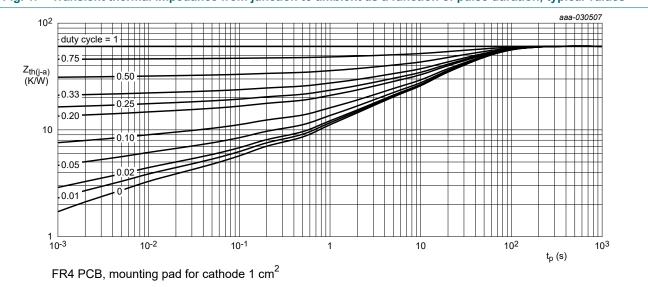


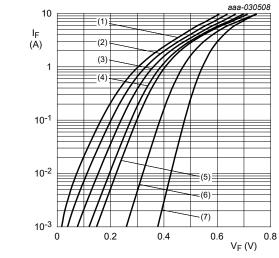
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per diode (ı	unless otherwise specified	1)					
$V_{(BR)R}$	reverse breakdown voltage	I _R = 1 mA; T _j = 25 °C	[1]	60	-	-	V
V _F	forward voltage	I _F = 0.5 A; T _j = 25 °C	[1]	-	440	510	mV
		I _F = 1 A; T _j = 25 °C	[1]	-	470	540	mV
		I _F = 4 A; T _j = 25 °C	[1]	-	580	660	mV
		I _F = 4 A; T _j = -40 °C	[1]	-	630	720	mV
		I _F = 4 A; T _j = 125 °C	[1]	-	520	610	mV
I _R	reverse current	V _R = 10 V; T _j = 25 °C	[1]	-	0.14	0.9	μA
		V _R = 40 V; T _j = 25 °C	[1]	-	0.18	1.2	μΑ
		V _R = 60 V; T _j = 25 °C	[1]	-	0.3	1.8	μΑ
		V _R = 60 V; T _j = 125 °C	[1]	-	0.5	3	mA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C		-	560	-	pF
		$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 ^{\circ}\text{C}$		-	180	-	pF
t _{rr}	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 \text{ °C}$		-	17	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A/}\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	11	-	ns
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	460	-	mV

^[1] Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

(1) $T_i = 175$ °C

(2) $T_i = 150 °C$

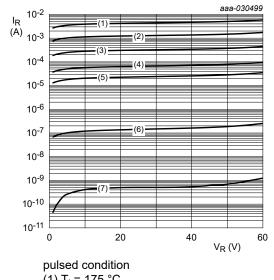
(3) $T_i = 125 °C$

 $(4) T_i = 100 °C$

 $(5) T_i = 85 ^{\circ}C$ (6) $T_i = 25 \,^{\circ}\text{C}$

 $(7) T_i = -40 ^{\circ}C$

Fig. 3. Forward current as a function of forward voltage; typical values



(1) $T_i = 175 \, ^{\circ}C$

 $(2) T_i = 150 ^{\circ}C$

(3) $T_i = 125 °C$

 $(4) T_i = 100 °C$

 $(5) T_i = 85 ^{\circ}C$ (6) $T_i = 25 \,^{\circ}\text{C}$

 $(7) T_i = -40 ^{\circ}C$

Fig. 4. Reverse current as a function of reverse voltage; typical values

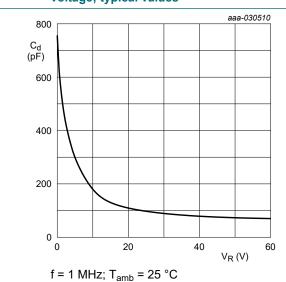
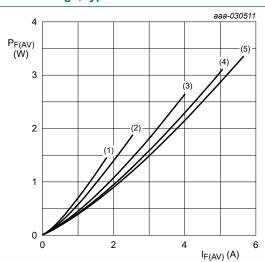


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



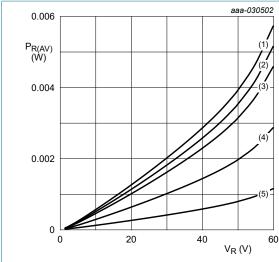
T_i = 100 °C $(1) \delta = 0.1$

(2) $\delta = 0.2$

 $(3) \delta = 0.5$

 $(4) \delta = 0.8$ (5) $\delta = 1$; DC

Average forward power dissipation as a Fig. 6. function of average forward current; typical values



 $T_j = 100 \,{}^{\circ}\text{C}$

 $(1) \delta = 1; DC$

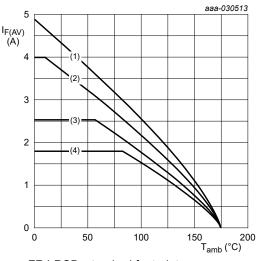
 $(2) \delta = 0.9$

 $(3) \delta = 0.8$

 $(4) \delta = 0.5$

 $(5) \delta = 0.2$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_i = 175 °C

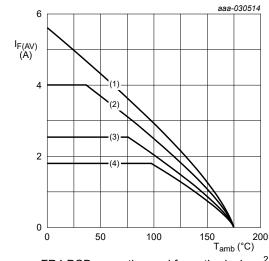
 $(1) \delta = 1$; DC

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

T_i = 175 °C

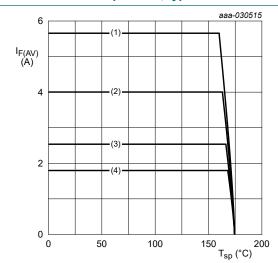
(1) $\delta = 1$; DC

 $(2) \delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



 $T_i = 175 \,{}^{\circ}\text{C}$

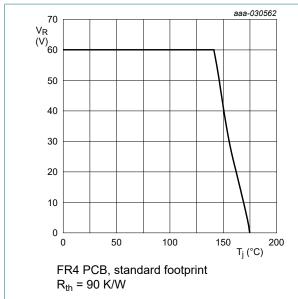
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

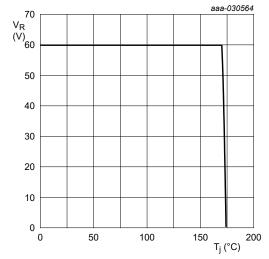


aaa-030563 70 (V) (O) 50 40 30 20 10 50 100 150 FR4 PCB, mounting pad for cathode 1 cm²

 $R_{th} = 70 \text{ K/W}$

of junction temperature; typical values

Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



Soldering point of cathode tab $R_{th} = 7 \text{ K/W}$

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

11. Test information

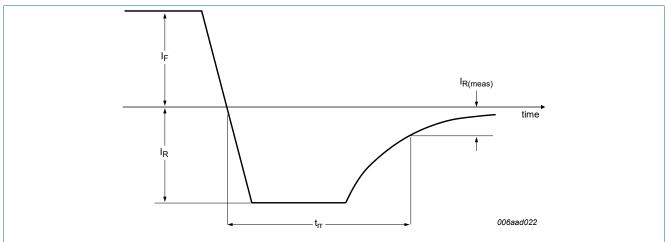


Fig. 14. Reverse recovery definition; step recovery

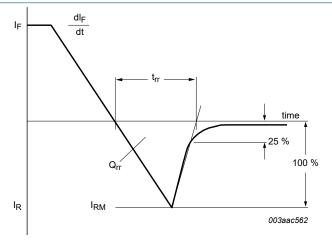


Fig. 15. Reverse recovery definition; ramp recovery

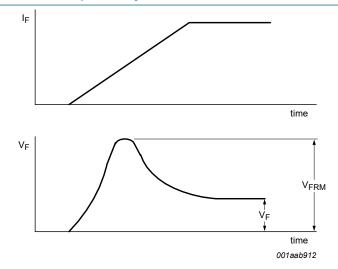
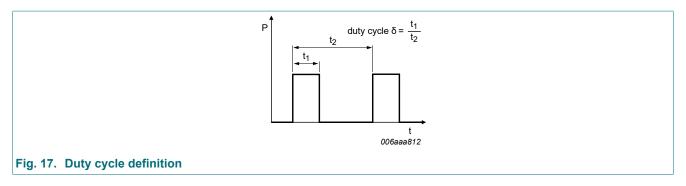


Fig. 16. Forward recovery definition



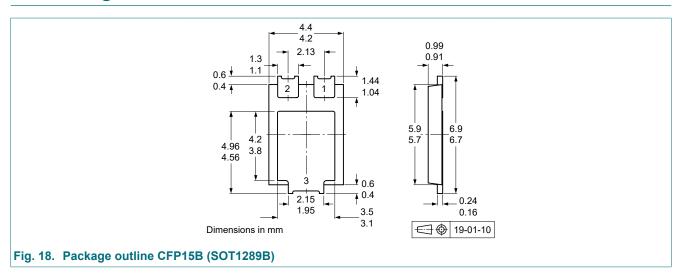
The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

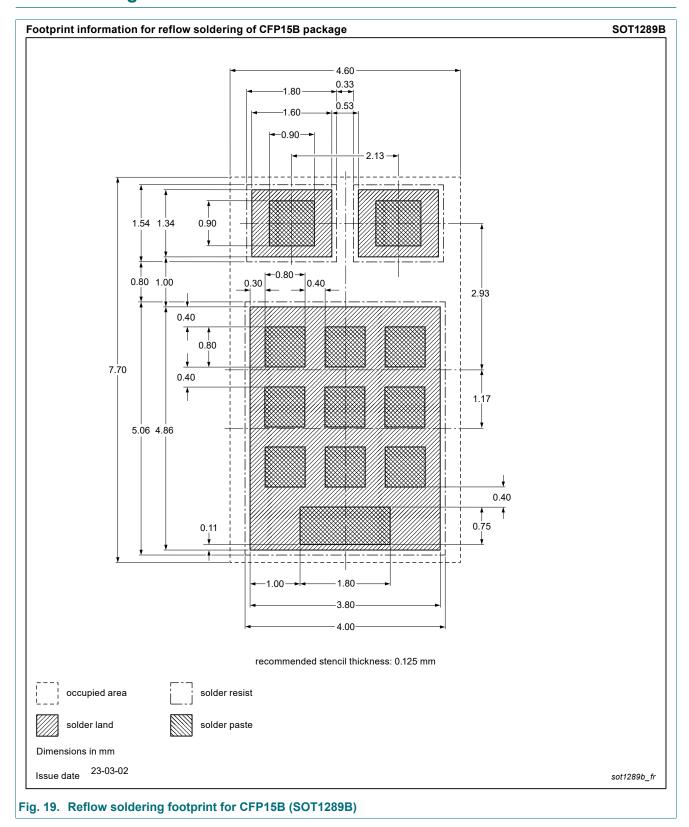
 $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_{M} \times \sqrt{\delta}$

with $I_{\mbox{\scriptsize RMS}}$ defined as RMS current.

12. Package outline



13. Soldering



14. Revision history

Table 8. Revision history

rabic of revision mistory				
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG060T080CLPE v.4	20240715	Product data sheet	-	PMEG060T080CLPE v.3
Modifications:	Reflow soldering	g footprint: Stencil design	for solder paste	printing changed.
PMEG060T080CLPE v.3	20230401	Product data sheet	-	PMEG060T080CLPE v.2
PMEG060T080CLPE v.2	20200427	Product data sheet	-	PMEG060T080CLPE v.1
PMEG060T080CLPE v.1	20200304	Objective data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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